



Att. Docket No. 10191/1690

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. Serial No. : 09/762,985 Confirmation No. 2674

Title : DEVICE AND METHOD FOR
ETCHING A SUBSTRATE USING
AN INDUCTIVELY COUPLED PLASMA

Applicant(s) : Volker BECKER et al.

Filed : May 8, 2001

TC/A.U. : 1763

Examiner : Luz L Alejandro Mulero

Docket No. :

10191/1690 *I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to:*

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on

Date: *12/14/2004*

Signature: *[Handwritten signature of Aaron C. Deditch]*

AARON C. DEDITCH
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AMENDMENT AFTER A FINAL OFFICE ACTION

SIR:

In response to the Final Office Action mailed on September 29, 2004 (the three-month response date for which is December 29, 2004), please reconsider the above-identified application based on the following:

Amendments to the Claims are reflected in the listing of the claims which begins on page 2 of this paper.

Remarks begin on page 9 of this paper.

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